OES TECHNOLOGIES

Proven Strip and Seal Defect Detection

Innovative, in-process inspection of wire stripping and seal insertion with 100% traceability.

WireScan™ B-Series

Automated inspection

Inspecting your wire stripping and seal loading process is critical to controlling errors. By automating this task in-process, you gain 100% confidence that your wire ends are ready for the next process.

Seamless integration into high-speed wire transfer machines

No-Contact, In-Process Monitoring

- The optical sensor projects a parallel beam which is then interrupted as the wire end is transferred through the sensing window
- The resulting image profile is analyzed by comparison to a reference or "learned" profile image

Wire Strip Inspection

- Identifies wire strip defects such as high/low insulation shoulder, pulled strand, splayed strands, and improper wire end position

Seal Insert Inspection

- Identifies seal loading defects such as lack of seal presence, reversed orientation, poor position, and skewed seal

WireScan Software

- User-friendly software is loaded onto the machine PC for set-up, configuration and operator control
- Installed onto Windows platform and runs in the background
- Sends "pop-ups" to the mainscreen display to indicate inspection status and flashs if a defect occurs
- Displays strip and/or seal inspection image

100% Traceability

- Wire strip and seal insertion data can be optionally logged and recalled by time stamp

Machine Integration

- The *WireScan* B-Series consists of the LPA56B optical sensor and software which resides on the machine PC
- Ideal for integration onto both existing and new wire processing machines
- I/O interface connects directly with the machine for control of defective parts
- *WireScan* works with all wire sizes including small cross-section wire

Flexible Installation

- Available with various options for physical mounting and electrical interfacing with a wide range of automatic machines

WireScan™ B-Series

Machine Applications	
Automatic Press - OEM	✓
Automatic Press - Retrofit	✓

Technical Specs

Supply Voltage	Voltage 24VDC @200mA +/- 10%
Communications	1 RS232
Resolution	0.125mm [.005"]
Inspection Window	16mm [.63"]
Inputs	2 - 24VDC optically isolated
Outputs	2-24VDC solid state 300mA max or 2-1A@ 24VDC
Electrical Connector	Application specific cable (optional)
Mounting	Mounting brackets (optional)
Dimensions	72 x 147 x 19 mm 2.83 x 5.75 x .75 inch

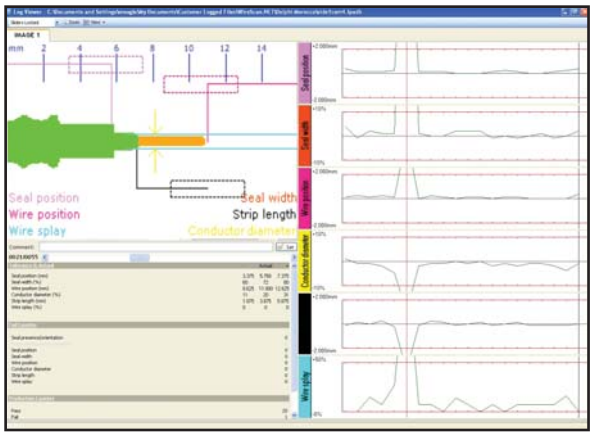
WIREScan™ LPA56B

The *WireScan* B-Series Laser Profile Analyser is a compact optical sensor for strip and seal inspection. The unit projects a 16mm sensing window. As the wire passes through the sensing window, an image of the wire is captured with a resolution of 0.125mm.

Using OES's proven algorithms, the image profile of each wire sample is compared with the "learned" standard profile image and a determination is made if the sample is a "success" or "fail".

WireScan B-Series package typically includes:

- LPA56B Unit
- *WireScan for Windows*
- Mounting bracket
- Electrical interface cable



About OES Technologies

Since 1979, OES has provided world-leading manufacturers with process monitoring and control solutions. OES's powerful wire crimp analysis technology is made available across their *ForceView* and *ForceWorx* product lines. The *Exceed* QPM System, along with their *WireScan* Inspection Systems, empowers wire processors with 100% verification and traceability of their complete production cycle. OES also offers *SenFit* sensors for small gauge wire crimping, *WireChop* to destroy defective parts and the *Examiner* Kit for complete press analysis.

ISO 9001 2008
FM 64157

4056 Blakie Road, London, ON N6L 1P7
Phone: 519-652-5833
Email: technologies@oes-inc.com